



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP HSR6602-G Router(JG353A)

HP HSR6602-XG Router(JG354A)

HP HSR6602-G TAA-compliant Router(JG776A)

HP HSR6602-XG TAA-compliant Router((JG777A))

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
tweezers	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws for mounting angle 1, and then remove the mounting angle 1 from the rack or cabinet.
2. Unscrew the screws on mounting angle 2, and then remove the mounting angle 2.
3. Remove all of the labels.
4. Unscrew the screws on fan-assembly 3, and then remove the fan-assembly 3.
5. Unscrew the screws on power mask 4, and then remove the power mask 4.
6. Remove the blank panel 5.
7. Unscrew the screws on top cover 6, and remove the top cover 6.
8. Unscrew the screws on power bracket 7, and then remove power bracket 7.
9. Unscrew the screws on PCB 8, and then remove PCB 8.
10. Unscrew the screws on PCB 9, and remove PCB 9.
11. Unscrew the screws on PCB 10, and remove PCB 10.
12. Remove shielding fingers 11.
13. Unscrew all the screws on the fan-assembly 3, and remove PCB 3.4.
14. Clear the yellow adhesive, if had, by the tweezers.
15. Pry the button battery up from socket.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

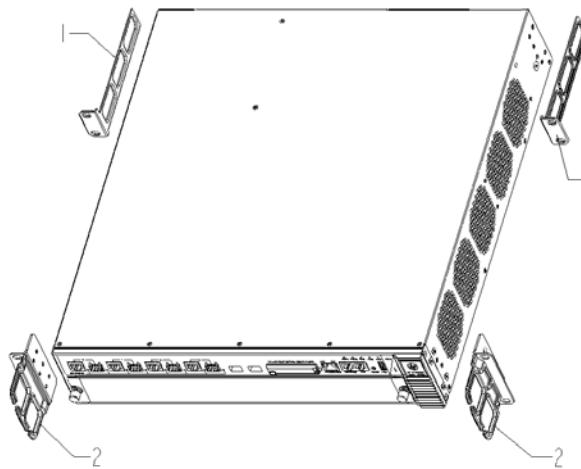


Figure 1 Remove the mounting angle 2

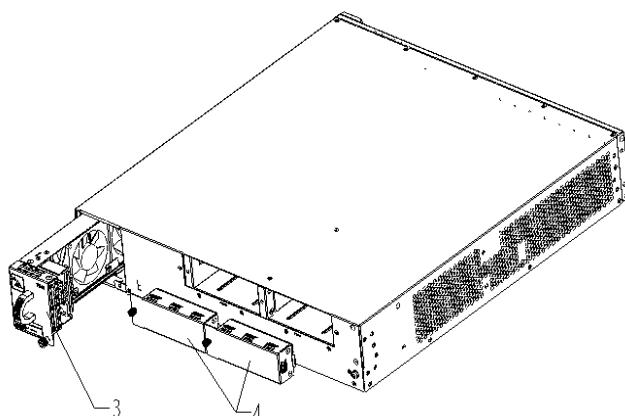


Figure 2 Treatments to rear panel

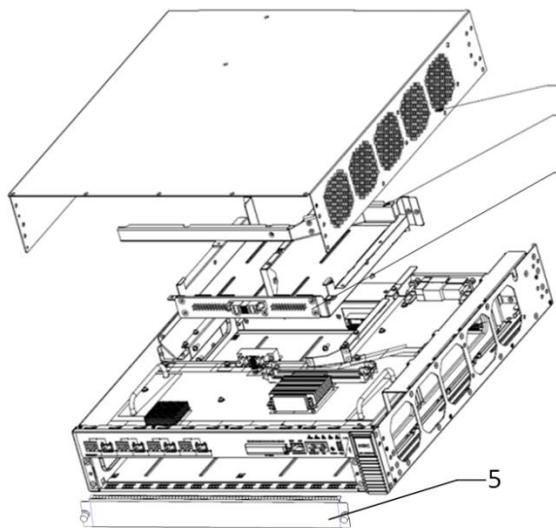


Figure 3 Remove top cover 6 and PCB 8

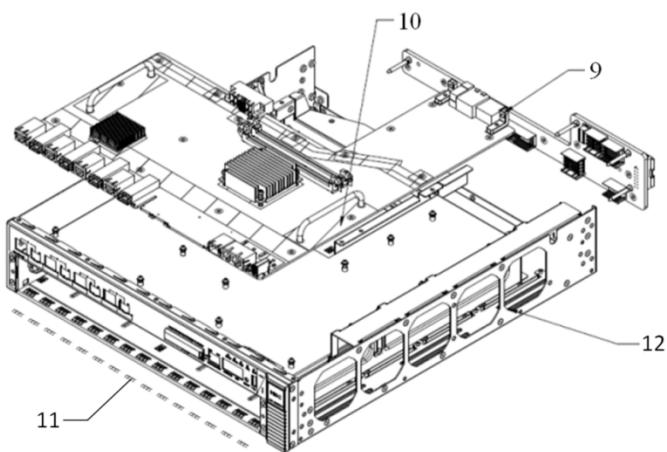


Figure 4 Remove PCB 9 and PCB 10

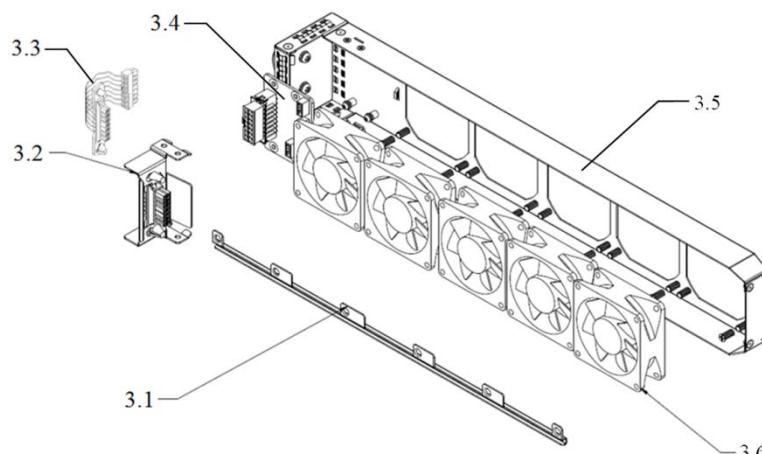


Figure 5 Treatments to Fan assembly 3

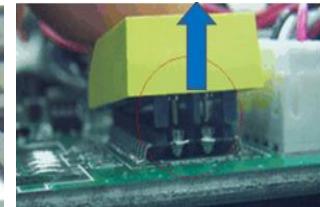


Figure 6 Clear the yellow adhesives by the tweezers

Figure 7 Pry up the button battery

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	84	0.8%		Fe recycling
2		Fe	150	1.4%		Fe recycling
3	3.1	Fe	42	0.4%		Fe recycling
	3.2	Fe	41	0.4%		Fe recycling
	3.3	Cable	10	0.1%		
	3.4	Complex PCB	10	0.1%	The surface of PCB is greater than 10 square centimeters;	
	3.5	Fe	383	3.6%		Fe recycling
	3.6	PC	50*5	2.4%		
4		Fe	96*2	1.8%		Fe recycling
5		Fe	313	3.0%		Fe recycling
6		Fe	2515	23.7%		Fe recycling
7		Fe	759	7.2%		Fe recycling
8		Complex PCB	100	0.9%	The surface of PCB is greater than 10 square centimeters;	
9		Complex PCB	250	2.4%	The surface of PCB is greater than 10 square centimeters;	
10		Complex PCB	1200	11.3%	The surface of PCB is greater than 10 square centimeters;	
11		Be-Cu	6	0.1%		Cu recycling
12		Fe	4300	40.5%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2012.11.21	V0	Wu Xuejun	Initial version
2013.07.19	V1	Liu Ziye	Add the module JG776A and JG777A